



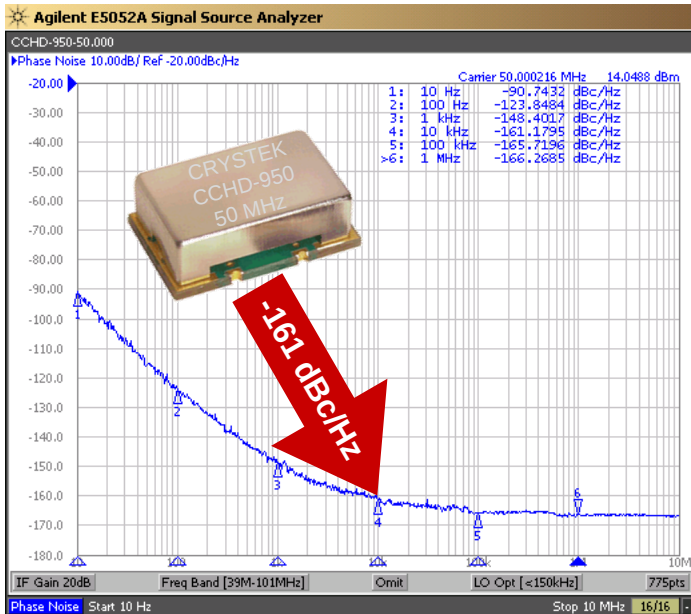
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CCHD-950 Model
9×14 mm SMD, 3.3V, HCMOS

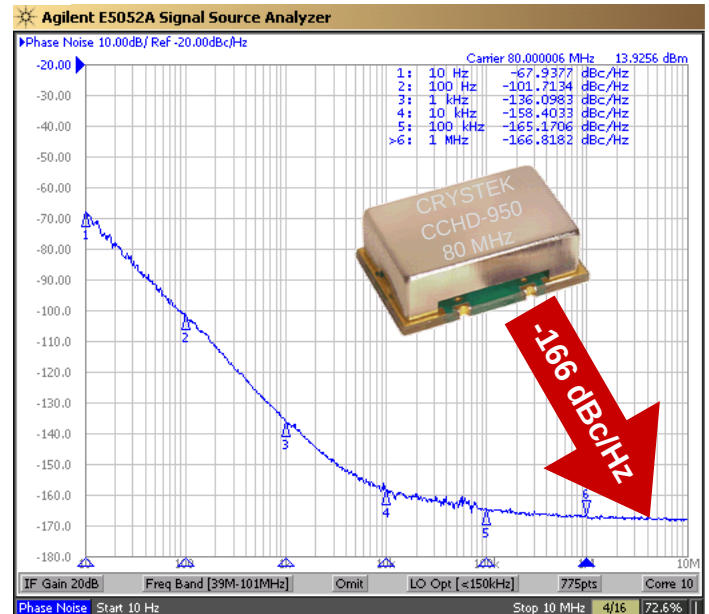


CCHD-950 Ultra-Low Phase Noise Oscillator

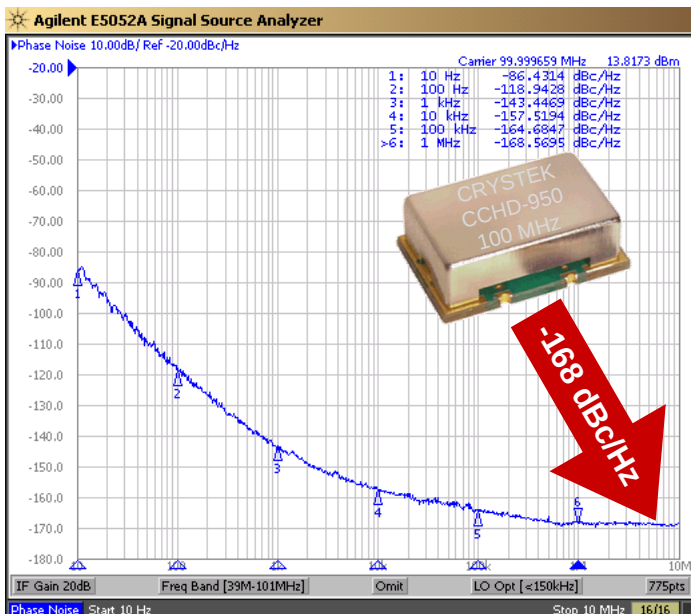
50 MHz HCMOS 3.3V



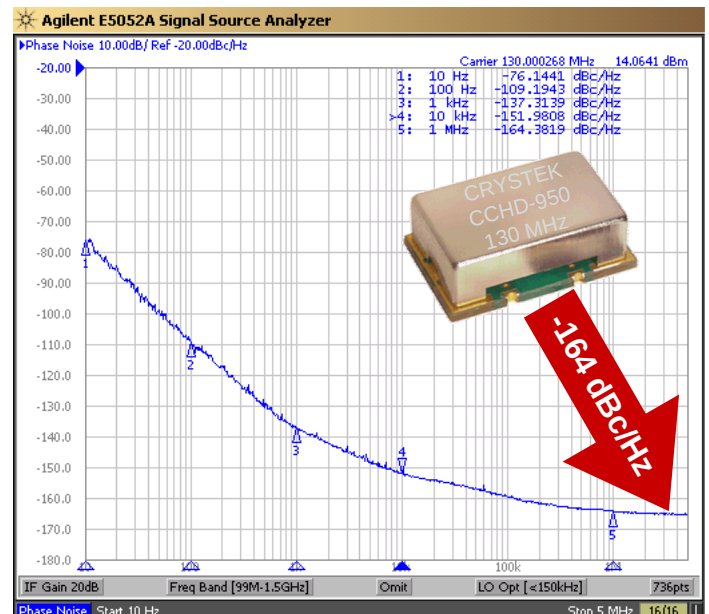
80 MHz HCMOS 3.3V



100 MHz HCMOS 3.3V



130 MHz HCMOS 3.3V



Model CCHD-950 is a 45 MHz to 130 MHz HCMOS Clock Oscillator. High Q crystal and 3rd overtone technology provides Ultra-Low Phase Noise and Low-Jitter performance with an HCMOS output. Features include -165 dBc/Hz phase noise floor with 3.3 Vdc input voltage, -40°C to +85°C operating temperature, and 9×14 mm SMT package. The oscillator has no sub-harmonics.

Applications include High Definition TV, Avionics
Low Phase Signal Sources, and Test and Measurement.

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CCHD-950

Ultra-Low Phase Noise Oscillator



CCHD-950 Model

9x14 mm SMD, 3.3V, HCMOS

Frequency Range: 45 MHz to 130 MHz
Temperature Range: 0°C to +70°C
 (Option M) -20°C to +70°C
 (Option X) -40°C to +85°C
Storage: -45°C to 90°C
Input Voltage: 3.3V ±0.3V
Input Current: 15mA Typical, 25mA Max
Output: HCMOS
Symmetry: 45/55% Max @ 50% Vdd
Rise/Fall Time: 3nsec Max @ 20% to 80% Vdd
Logic: "0" = 10% Vdd Max
 "1" = 90% Vdd Min
Load: 15pF
Output Current: ±24mA Max
Jitter: 12kHz~80MHz 0.5psec Typical, 1psec RMS Max
Phase Noise Typical: See plots
Phase Noise Floor: -165dBc/Hz Typical, -160dBc/Hz Max
Sub-harmonics: None
Aging: <3ppm 1st year, <1ppm thereafter

CCHD-950 Options:

Temperature Range: 0°C to +70°C (±20ppm, ±25ppm, ±50ppm)
 -20°C to +70°C (±25ppm, ±50ppm)
 -40°C to +85°C (±25ppm, ±50ppm)

Part Number Example:

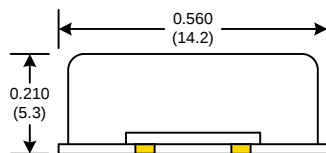
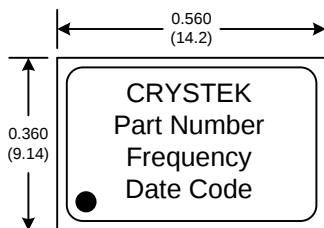
CCHD-950X-25-100.000 = 3.3V, 45/55, -40°C to +85°C (±25ppm), 100 MHz

Mechanical:

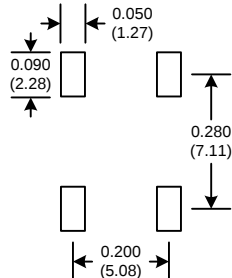
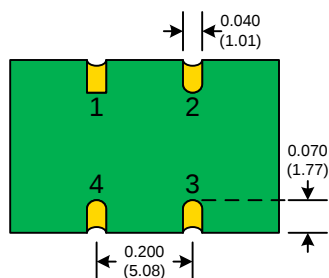
Shock: MIL-STD-883, Method 2002, Condition B
 Solderability: MIL-STD-883, Method 2003
 Vibration: MIL-STD-883, Method 2007, Condition A
 Solvent Resistance: MIL-STD-202, Method 215
 Resistance to Soldering Heat: MIL-STD-202, Method 210, Condition I or J

Environmental:

Thermal Shock: MIL-STD-883, Method 1011, Condition A
 Moisture Resistance: MIL-STD-883, Method 1004

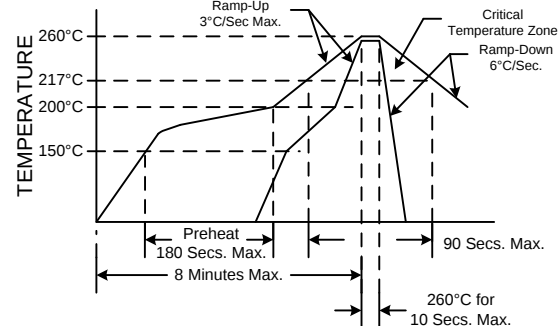


SUGGESTED PAD LAYOUT



Pad	Connection
1	NC
2	GND
3	OUT
4	Vdd

RECOMMENDED REFLOW SOLDERING PROFILE



NOTE: Reflow Profile with 240°C peak also acceptable.

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